

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. 1. (Currently Amended) A method of manufacturing a semiconductor device, comprising:
forming terminal portions convexly protruding on a surface of first conductive foil by
etching the first conductive foil except portions to become terminals;
superimposing a resin ~~sheet~~ on the first conductive foil such that the terminal portions are
embedded in ~~[[the]]~~ a resin sheet;
constructing a laminated sheet by superimposing second conductive foil on the resin
~~sheet~~;
forming a conductive pattern by etching the second conductive foil;
electrically connecting the conductive pattern and the terminal portions;
electrically isolating the terminal portions from each other;
~~firmly~~ fixing a semiconductor element to the laminated sheet and electrically connecting
the semiconductor element and the conductive pattern; and
forming sealing resin on a surface of the laminated sheet such that the semiconductor
element is covered by the sealing resin.
2. (Original) The method according to claim 1, wherein the terminal portions are
electrically isolated from each other by etching the first conductive foil from a back thereof.
3. (Currently Amended) The method according to claim 1, wherein the resin sheet is
made of soluble resin, and ~~side surfaces of~~ the terminal portions are exposed by removing the
resin sheet.

4. (Currently Amended) The method according to claim 1, wherein the semiconductor element is fixed ~~connected~~ face-up, and an electrode of the semiconductor element and the conductive pattern are connected through a fine metallic wire.

5. (Currently Amended) The method according to claim 1, wherein the semiconductor element is mounted face-down, and an electrode of the semiconductor element and the conductive pattern are connected through a bump electrode.